MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

PLED

SSL34F-MS

Product specification





FEATURES

- Ideal for surface mount applications
- Easy pick and place
- Built-in strain relief
- Low forward voltage drop
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- Easy pick and place
- Built-in strain relief
- Low forward voltage drop

MACHANICAL DATA

- Case: Molded plastic
- Epoxy: UL 94V-0 rate flame retardant
- Metallurgically bonded construction
- Polarity: Color band denotes cathode end
- Mounting position: Any

VOLTAGE RANGE

40 Volts

CURRENT

3.0 Ampere

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION	Marking
		SSL34F
SMAF		



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25 C ambient temperature unless otherwies specified.

Single phase half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

TYPE NUMBER		SSL34F-MS	UNITS
Maximum Recurrent Peak Reverse Voltage		40	V
Maximum RMS Voltage		28	V
Maximum DC Blocking Voltage		40	V
Maximum Average Forward Rectified Current			
See Fig. 1		3.0	A
Peak Forward Surge Current, 8.3 ms single half sine-wa	ave		
superimposed on rated load (JEDEC method)		50	A
Maximum Instantaneous Forward Voltage at 2.0A		0.46	V
Maximum DC Reverse Current	Ta=25 C	0.2	mA
at Rated DC Blocking Voltage	Ta=125 [®] C	30	mA
Typical Junction Capacitance (Note1)		240	pF
Typical Thermal Resistance R JA (Note 2)		88	C/W
Operating Temperature Range TJ		-55 to +125	°C
Storage Temperature Range Tsrg		-55 to +150	"C

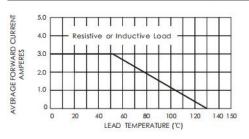
NOTES:

- 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
- 2. P.C.B. mounted with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas



RATING AND CHARACTERISTIC CURVES (SSL34F-MS)







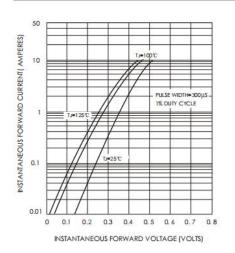


FIG.5-TYPICAL JUNCTION CAPACITANCE

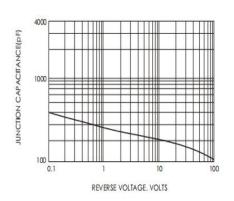


FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

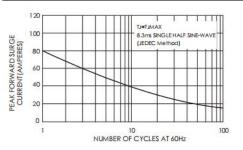
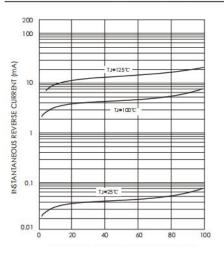
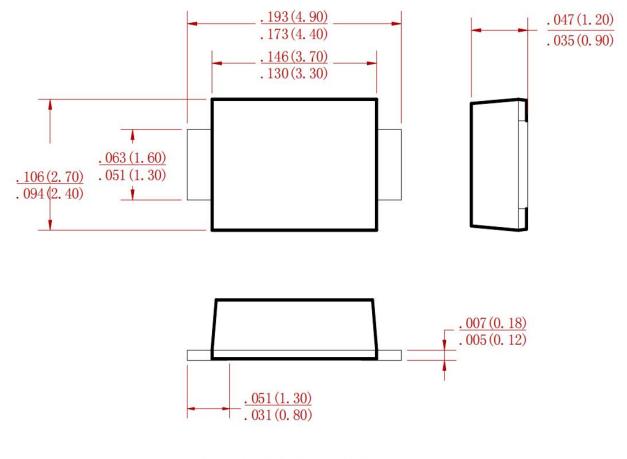


FIG.4-TYPICAL REVERSE CHARACTERISTICS





PACKAGE MECHANICAL DATA



Dimensions in inches and (millimeters)

REEL SPECIFICATION

P/N	PKG	QTY
SSL34F-MS	SMAF	3000



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